



HDMI 2.0, DisplayPort 1.2 Video Switch

Features

- → 4-lane, 1:2 mux/demux that will support RBR, HBR1, or HBR2
- → Data rate: 3.4 Gbps to 6.0 Gbps for high data channels
- → Supports DDC with HPD channel mux/demux @ HDMI
- → Supports 720 Mbps high-speed DP AUX @ DP
- → -1.7 dB Insertion Loss for Dx channels @ 3.0 GHz
- → -3 dB Bandwidth for Dx channels: 4.8 GHz
- → Return loss for Dx channels @ 3.0 GHz: -16 dB
- → Low Crosstalk for high speed channels: -25 dB@6.0 Gbps
- → Low Off Isolation for high speed channels: -22dB@6.0 Gbps
- → Low channel-to-channel skew, 35ps max
- → Low Bit-to-Bit Skew, 5ps typ (between '+' and '-' bits)
- → V_{DD} Operating Range: 3.3V +/-10%
- → ESD Tolerance: 2kV HBM
- → Packaging (Pb-free & Green): 42 TQFN (ZHE)

Description

The PI3WVR12412 is a multi-standard video switch with wide voltage range capability. It supports HDMI 2.0, DisplayPort 1.2, and emerging and proprietary standard.

PI3WVR12412 can pass high-speed signals up to 1.2 V peak-to-peak differential with a common-mode voltage from 0 to 3.4V for TMDS signal.

The wide voltage range allow DC-coupled multi-standard operation. Eliminating AC coupling capacitors saves board space and improves signal integrity for dense PCB design. The high speed channels can also pass 0V-3.3V CMOS signals up to 1MHz.

In addition to four high-speed lanes, PI3WVR12412 also switches the DDC and HPD signals or AUX and HPD signals using the DDC/ AUX and HPD channel mux/demux.

Application

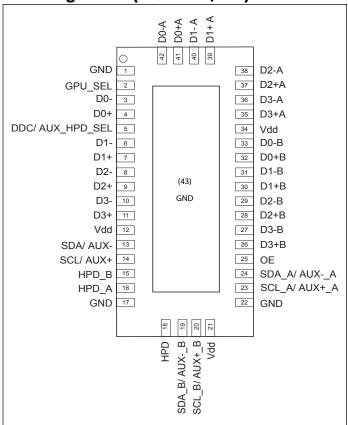
- → Routing of HDMI 2.0 video signals with low signal attenuation between source and sink for 4K2K ultra high definition video display and broadcast video equipment.
- → Routing of DisplayPort video signals with low signal attenuation between source and sink for PC and monitor.

Block Diagram D0+ D0+A D0-D0-A D1+ D1+A D1-D1-A D2+ D2+A D2-D2-A D3+ D3+A D3-D3-A D0+B D0-B D1+B D1-B D2+B D2-B D3+B D3-B SCL/ AUX+ SCL A/ AUX+ A SDA/ AUX-SDA A/ AUX- A HPD HPD A SCL B/ AUX+ B SDA B/ AUX- B HPD B GPU SEL Logic DDC/ AUX HPD SEL Control ΟF





Pin Assignment (TQFN-42, ZH)



Truth Table

Control				Switch Funct	ion	
OE	GPU_SEL DDC/ AUX_HPD_SEL		D0-D3	DDC/ AUX	HPD	
High	Low	Low	A	DDC A/ AUX A	HPD A	
High	Low	High	A	DDC B/ AUX B	HPD B	
High	High	Low	В	DDC A/AUX A	HPD A	
High	High	High	В	DDC B/ AUX B	HPD B	
Low	X	x	Hi-Z	Hi-Z	Hi-Z	

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Pin Description

Pin#	Pin Name	Signal Type	Description
1	GND	Ground	Ground
2	GPU_SEL	I	switch logic control
3	D0-	I/O	negative differential signal 0 for COM port
4	D0+	I/O	positive differential signal 0 for COM port
5	DDC/ AUX_HPD_SEL	I	Switch logic control for DDC/ AUX and HPD
6	D1-	I/O	negative differential signal 1 for COM port
7	D1+	I/O	positive differential signal 1 for COM port
8	D2-	I/O	negative differential signal 2 for COM port
9	D2+	I/O	positive differential signal 2 for COM port
10	D3-	I/O	negative differential signal 3 for COM port
11	D3+	I/O	positive differential signal 3 for COM port
12	VDD	Power	3.3V +/-10% power supply
13	SDA/ AUX-	I/O	SDA signal for DDC COM port, or negative differential signal for AUX COM port
14	SCL/ AUX+	I/O	SCLl signal for DDC COM port, or positive differential signal for AUX COM port
15	HPD_B	I/O	HPD for port B
16	HPD_A	I/O	HPD for port A
17	GND	Ground	Ground
18	HPD	I/O	HPD for COM port
19	SDA_B/ AUXB	I/O	SDA signal for DDC, port B, or negative differential signal for AUX COM port
20	SCL_B/ AUX+_B	I/O	SCL signal for DDC, port B, or positive differential signal for AUX COM port
21	VDD	Power	3.3V +/-10% power supply
22	GND	Ground	Ground
23	SCL_A/ AUX+_A	I/O	SCL signal for DDC, port A, or positive differential signal for AUX COM port
24	SDA_A/ AUXA	I/O	SDA signal for DDC, port A, or negative differential signal for AUX COM port
25	OE	I	output enable. if OE is high, IC is enabled. if OE is low, IC is power down and all I/Os are Hi-Z
26	D3+B	I/O	positive differential signal 3 for portB
27	D3-B	I/O	negative differential signal 3 for portB
28	D2+B	I/O	positive differential signal 2 for portB
29	D2-B	I/O	negative differential signal 2 for portB
30	D1+B	I/O	positive differential signal 1 for portB
31	D1-B	I/O	negative differential signal 1 for portB





Pin#	Pin Name	Signal Type	Description
32	D0+B	I/O	positive differential signal 0 for portB
33	D0-B	I/O	negative differential signal 0 for portB
34	VDD	Power	3.3V +/-10% power supply
35	D3+A	I/O	positive differential signal 3 for port A
36	D3-A	I/O	negative differential signal 3 for port A
37	D2+A	I/O	positive differential signal 2 for port A
38	D2-A	I/O	negative differential signal 2 for port A
39	D1+A	I/O	positive differential signal 1 for port A
40	D1-A	I/O	negative differential signal 1 for port A
41	D0+A	I/O	positive differential signal 0 for port A
42	D0-A	I/O	negative differential signal 0 for port A
43	Center pad	Ground	Ground





Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	65°C to +150°C
Junction Temperature	
Supply Voltage to Ground Potential	0.5V to +4.2V
High Speed Data Channel	-0.5V to 3.8V
HPD_x, SDA_x, SCL_x	-0.5V to 5.5V
DC Input Voltage	0.5V to V _{DD}
DC Output Current	120mA
Power Dissipation	0.5W

Note: Stresses greater than those listed under MAXI-MUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Electrical Characteristics for Switching over Operating Range

 $(T_A = -40^{\circ}C \text{ to } +105^{\circ}C, V_{DD} = 3.3V \pm 10\%)$

Parameter	Description	escription Test Conditions ⁽¹⁾		Typ. (2)	Max.	Units	
v_{IH}	Input HIGH Voltage (SEL & OE)	Guaranteed HIGH level	d HIGH level 1.5				
V_{IL}	Input LOW Voltage (SEL & OE)	Guaranteed LOW level	0.75		0.75		
v_{IK}	Clamp Diode Voltage (HS Channel)	$V_{DD} = Max., I_{IN} = -18mA$		-1.6V	-1.8	V	
V _{IK}	Clamp Diode Voltage (DDC/ AUX, Cntrl)	$V_{\mathrm{DD}} = \mathrm{Max.}, I_{\mathrm{IN}} = -18\mathrm{mA}$		-0.7	-1.5		
IIH	Input HIGH Current	$V_{DD} = Max., V_{IN} = V_{DD}$			±5		
IIL	Input LOW Current	$V_{DD} = Max., V_{IN} = GND$			±5 μA		
I _{OFF_SB}	I/O leakage when part is off for sideband signals only (DDC/ AUX, HPD)	$V_{DD} = 0V$, $V_{INPUT} = 0V$ to 3.6V			20		
R _{ON_HS}	On resistance between input to output for high speed signals	$\begin{split} V_{INPUT,cm} &= 0 V \text{ to } 3.4 V, \\ V_{INPUT,diff} &< 1.2 V_{p\text{-}p,diff}, \\ V_{DD} &= 3.0 V, I_{INPUT} = 20 \text{mA} \end{split}$		11		Ohm	
R _{ON_DDC} / AUX	On resistance between input to output for side-band signals (DDC/AUX)	V_{DD} = 3.0V, Vinput = 0 to 3.3V, I_{INPUT} = 20mA		7		Ohm	
R _{ON_HPD}	On resistance between input to output for HPD channel	V_{DD} = 3.0V, Vinput = 0 to 3.0V, I_{INPUT} = 20mA		7		Ohm	
V _{DDC} / AUX_SS	Signal Swing Tolerance in DDC/ AUX path	$V_{DD} = 3.0V$	-0.5		5.5	V	
V _{HPD_I}	Input voltage on HPD path				5.5	V	
V _{HPD_O}	Output voltage tolerance on HPD path	HPD input from 3.3V to 5.25V		3.3	3.6	V	





Power Supply Characteristics

 $(T_A = -40^{\circ}C \text{ to } +105^{\circ}C)$

Parameter	Description	Test Conditions ⁽¹⁾	Min.	Typ. (2)	Max.	Units
I_{DD}	Power Supply Current	V_{DD} = 3.3V, V_{IN} = GND or V_{DD}		1	3	mA
I _{DD,Off}	Power Supply Current, Disabled	V_{DD} = 3.3V, V_{IN} = GND or V_{DD} , V_{OE} < V_{IL}		1	50	μΑ

Note:

- 1. For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at $V_{\rm DD}$ = 3.3V, $T_{\rm A}$ = 25°C ambient and maximum loading.

Dynamic Electrical Characteristics over Operating Range

 $(T_A = -40^{\circ} \text{ to } +105^{\circ}\text{C}, V_{DD} = 3.3\text{V} \pm 10\%)$

Parameter	Description	Test Conditions	(1)	Min.	Typ. (2)	Max.	Units
			f= 3.0 GHz		-25	-22	
V	Crosstalk on High Speed	See Fig. 1 for	f= 2.7 GHz		-28	-25	
X _{TALK}	Channels	Measurement Setup	f = 1.7 GHz		-31	-28	
			f = 1.35 GHz		-32	-28	dB
		See Fig. 2 for	f= 3.0 GHz		-22	-20	ав
	OFF Isolation on High Speed Channels	Measurement Setup	f= 2.7 GHz		-22	-20	
O_{IRR}			f = 1.7 GHz		-29	-26	
			f = 1.35 GHz		-30	-27	
T	Differential Insertion Loss on	@3.0 GHz (see figure 3)		-2.0	-1.7		10
I _{LOSS}	High Speed Channels	@5.4 Gbps (see figure 3)		-2.0	-1.7		dB
D.	Differential Return Loss on	@ 3.0 GHz (6.0Gb)		-16.0	-14	dB	
R _{loss}	high speed channels	@ 2.7 GHz (5.4Gbps)			-14.0		-12.5
BW_Dx±	Bandwidth -3dB for Main high speed path (Dx±)	See figure 3		3.7	4.8		GHz
BW_DDC/ AUX/ HPD	-3dB BW for DDC/ AUX and HPD signals	See figure 3		1.35	1.5		GHz

Note:

- $1. \ \ For Max. \ or Min. \ conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.$
- 2. Typical values are at $V_{\rm DD}$ = 3.3V, $T_{\rm A}$ = 25°C ambient and maximum loading.





Switching Characteristics

 $(T_A = -40^{\circ} \text{ to } +105^{\circ}\text{C}, V_{DD} = 3.3\text{V} \pm 10\%)$

Parameter	Description		Two	Max.	Units
rarameter	Description	Min.	Тур.	max.	Units
T_{pd}	Propagation delay (input pin to output pin) on all channels		80		ps
t _{b-b}	Bit-to-bit skew within the same differential pair of Dx± channels		5	7	ps
t _{ch-ch}	Channel-to-channel skew of Dx± channels			35	ps
Tsw a-b	time it takes to switch from port A to port B			0.1	us
Tsw b-a	time it takes to switch from port B to port A			0.1	us
Tstartup	V _{DD} valid to channel enable			10	us
Twakeup	Enabling output by changing OE from low to High			10	us





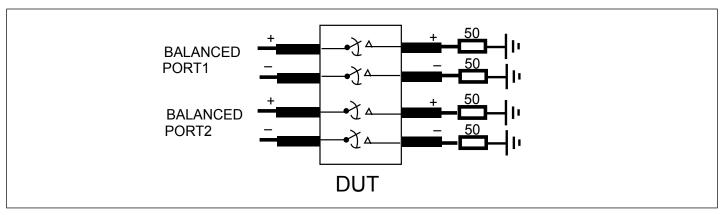


Fig 1. Crosstalk Setup

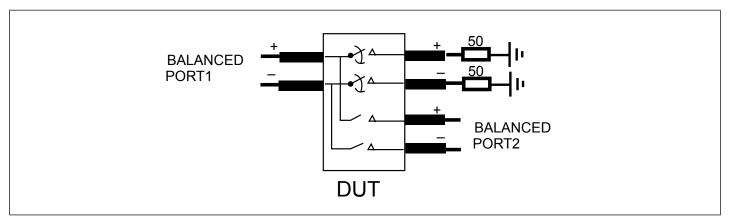


Fig 2. Off-isolation setup

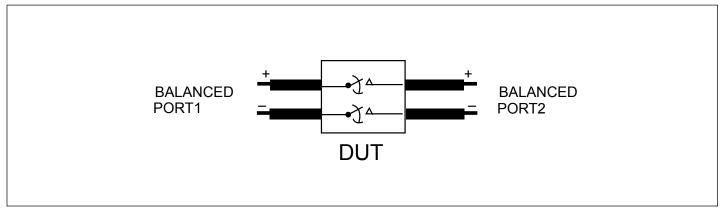
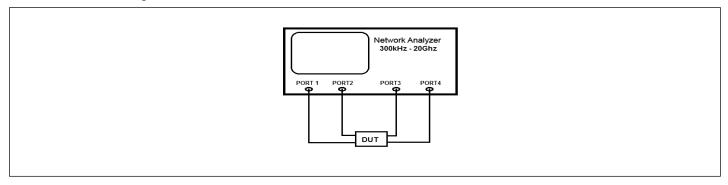


Fig 3. Differential Insertion Loss





Test Circuit for Dynamic Electrical Characteristics



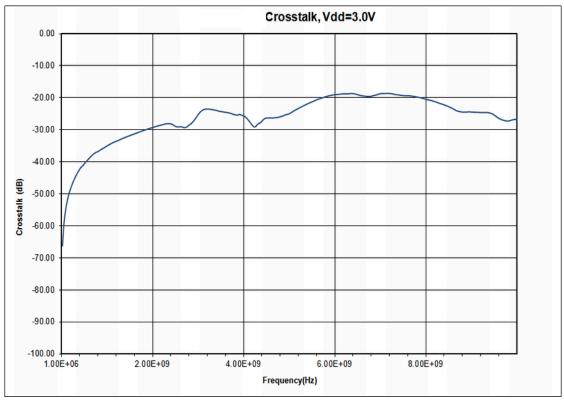


Fig 4. Crosstalk





Fig 5. Off Isolation



Fig 6. Insertion Loss



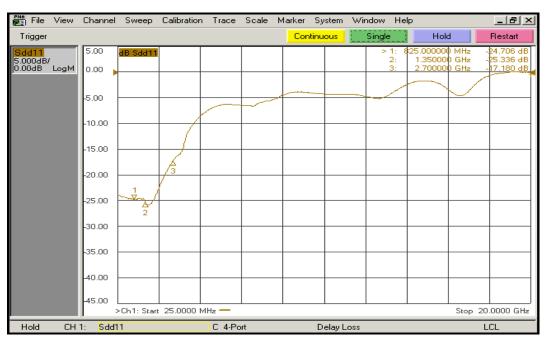


Fig 7. Return Loss

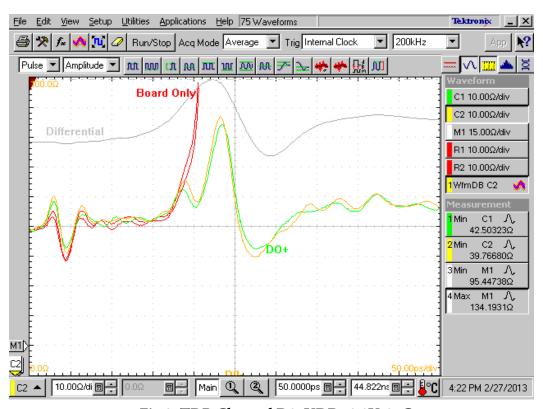
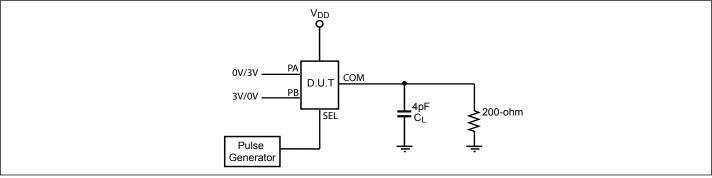


Fig 8. TDR Channel D0, VDD=3.0V, 25C





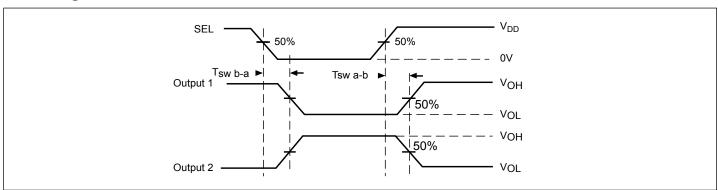
Test Circuit for Electrical Characteristics(1-4)



Notes:

- 1. C_L = Load capacitance: includes jig and probe capacitance.
- 2. R_T = Termination resistance: should be equal to $Z_{\mbox{OUT}}$ of the Pulse Generator
- 3. All input impulses are supplied by generators having the following characteristics: PRR \leq MHz, $Z_O = 50\Omega$, $t_R \leq$ 2.5ns, $t_F \leq$ 2.5ns.
- 4. The outputs are measured one at a time with one transition per measurement.

Switching Waveforms



Voltage Waveforms for Select Timing

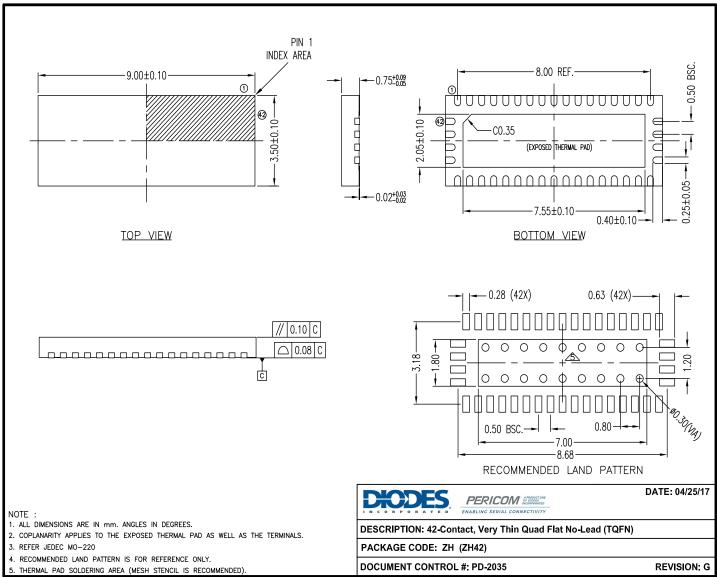
Test Condition

Output 1 Test Condition	Output 2 Test Condition		
PA = Low	PA = High		
PB = High	PB = Low		





Packaging Mechanical: 42ZH



17-0266

For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Code	Package Code	Package Description
PI3WVR12412ZHEX	ZH	42-contact, Very Thin Quad Flat No-Lead (TQFN) (W24)
PI3WVR12412ZHE+DRX ZH 42		42-contact, Very Thin Quad Flat No-Lead (TQFN) (W16)

Notes:

- · Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/
- E = Pb-free and Green
- X suffix = Tape/Reel





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